

PARA LIGHT ELECTRONICS CO., LTD.

11F., No. 8, Jiankang Rd., Zhonghe Dist., New Taipei City 235, Taiwan,Tel: 886-2-2225-3733Fax: 886-2-2225-4800E-mail: para@para.com.twhttp://www.para.com.tw

DATA SHEET

PART NO. : L-C150KGCT

REV : <u>C / 0</u>

CUSTOMER'S APPROVAL :

DCC :

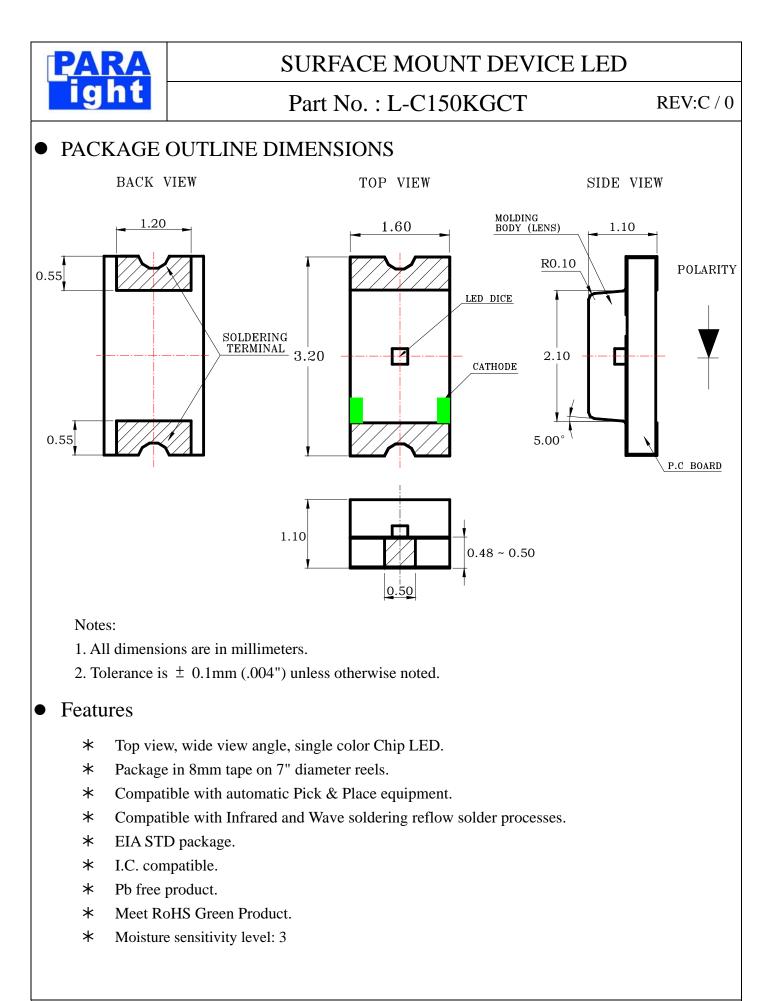
PAGE

1 of 12

DRAWING NO. : DS-71-03-0005

DATE : 2024-1-24

LD-R/E020



DRAWING NO. : DS-71-03-0005

DATE : 2024-1-24 PAGE 2 of 12



Part No. : L-C150KGCT

REV:C / 0

• Chip Materials

- * Dice Material : AlInGaP
- * Light Color : Super Green
- * Lens Color : Water Clear

• Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
Pd	Power Dissipation	60	mW
IPFPeak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)		60	mA
IF	Continuous Forward Current	30	mA
VR	Reverse Voltage	5	V
ESD	Electrostatic Discharge Threshold(HBM) ^{Note A}	2000	V
Topr	Operating Temperature Range	-40 ~ +85	°C
Tstg	Storage Temperature Range	-40 ~ +85	°C

Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

• Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Lumino s Intensity	IV	18.0	30.0	71.0	mcd	IF=20mA
Viewing Angle	2 0 1/2		130		deg	Note 2
Dominant Wavelength	λd	567	570	573	nm	IF=20mA
Forward Voltage	VF	1.9	2.05	2.3	V	IF =20mA
Reverse Current	IR			10	μA	VR = 5V

DATE : 2024-1-24 PAGE 3 of 12



Part No. : L-C150KGCT

REV:C / 0

• Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA			Forward Voltage(VF), Unit:V@20mA			
Bin Code	Min	Max	Bin Code	Min	Max	
М	18.0	28.0	4	1.90	2.00	
N	28.0	45.0	5	2.00	2.10	
Р	45.0	71.0	6	2.10	2.20	
			7	2.20	2.30	

Tolerance of each bin are $\pm 15\%$

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue), Unit: nm@20mA					
Bin Code	Min	Max			
GA	567.0	570.0			
GB	570.0	573.0			
GC	573.0	576.0			

Tolerance of each bin are ± 1 nm

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.

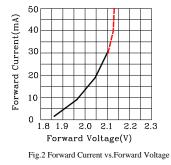


Part No. : L-C150KGCT

REV:C / 0

• Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)



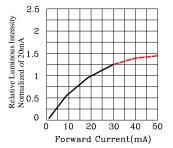
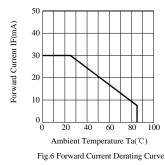


Fig.4 Relative Luminous Intensity vs.Forward Current



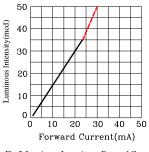
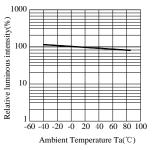
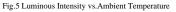


Fig.3 Luminous Intensity vs.Forward Current





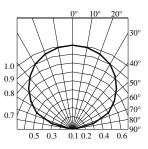


Fig.7 Relative Intensity vs.Angle

DRAWING NO. : DS-71-03-0005

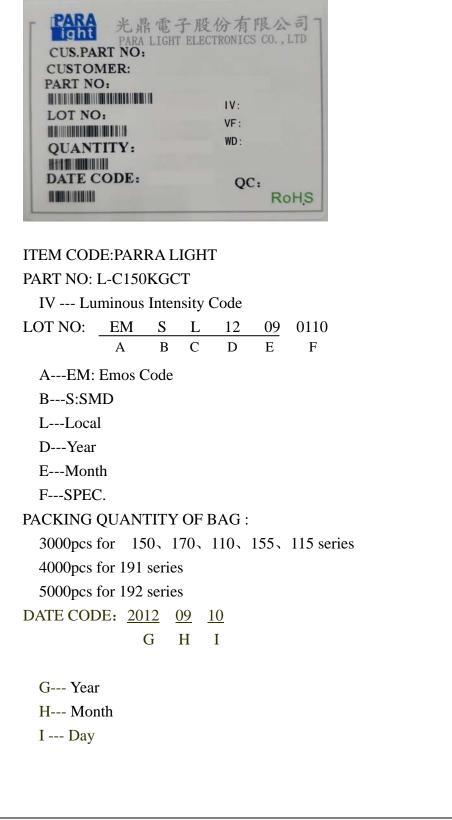
DATE : 2024-1-24 PAGE 5 of 12



Part No. : L-C150KGCT

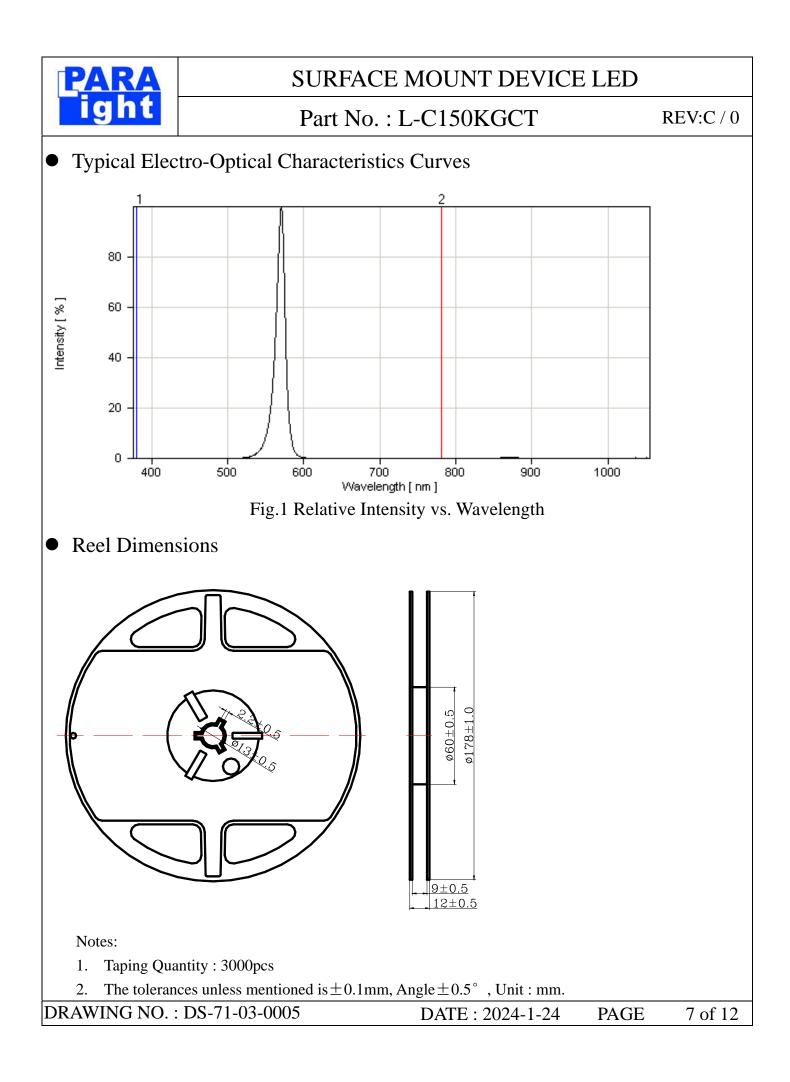
REV:C / 0

• Label Explanation



DRAWING NO. : DS-71-03-0005

DATE : 2024-1-24 PAGE 6 of 12



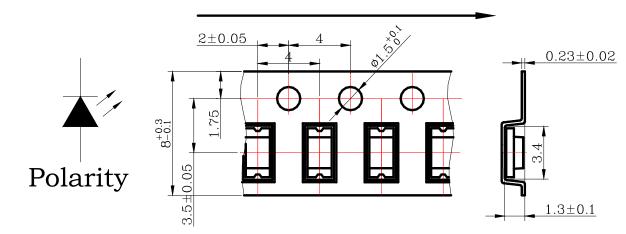


Part No. : L-C150KGCT

REV:C / 0

• Package Dimensions Of Tape And Reel

Progressive direction



Notes: All dimensions are in millimeters.

DRAWING NO. : DS-71-03-0005

DATE : 2024-1-24 PAGE 8 of 12



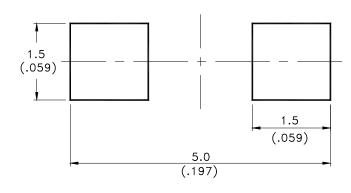
Part No. : L-C150KGCT

REV:C / 0

• Cleaning

- * If cleaning is required , use the following solutions for less than 1 minute and less than 40° C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

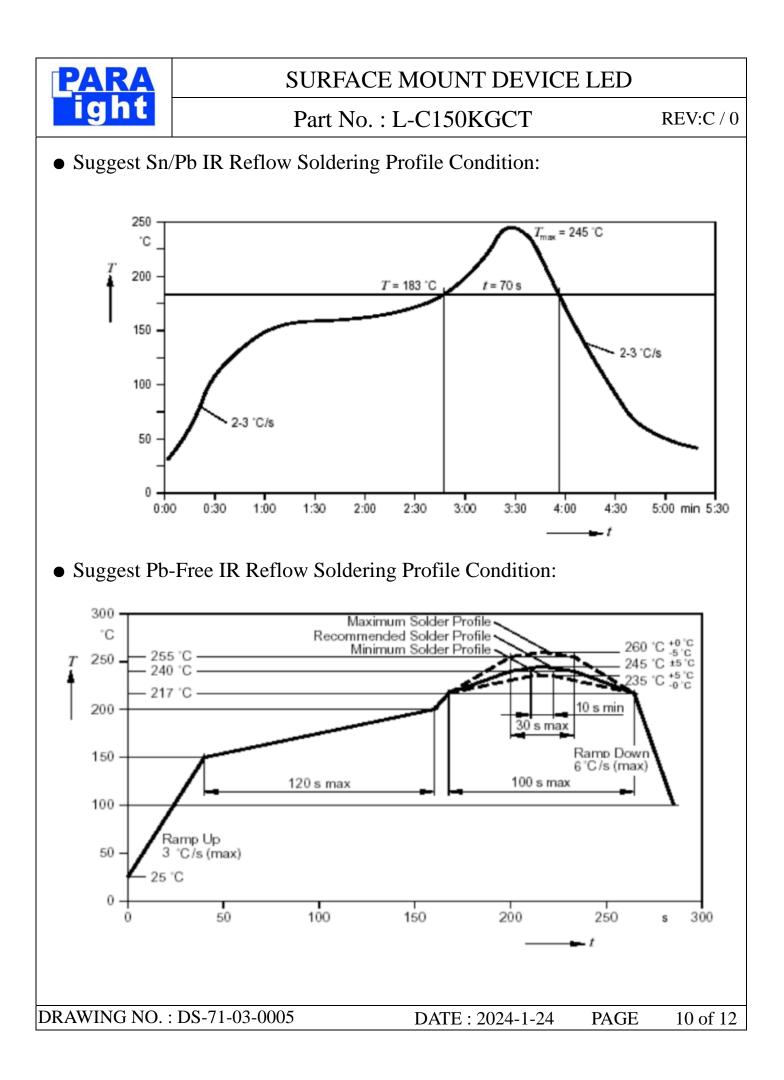
• Suggest Soldering Pad Dimensions



Direction of PWB camber

DRAWING NO. : DS-71-03-0005

DATE : 2024-1-24 PAGE 9 of 12





Part No. : L-C150KGCT

REV:C / 0

• CAUTIONS

1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.



SURFACE MOUNT DEVICE LED

ight	Part	No. : L-C150KGCT	R	EV:C / 0
Reflow Soldering :				
Pre-heat 120~150°	C, 120sec. MAX., Peak tempe	erature : 240°C Max. Soldering time : 10) sec Max.	
Soldering Iron : (N	ot recommended)			
Temperature 300°C	C Max., Soldering time : 3 sec.	. Max.(one time only), power dissipation	n of iron : 20W Max	. use SN60
solder of solder wit	th silver content and don't to t	ouch LED lens when soldering.		
Wave soldering :				
		, Solder wave 260°C Max, Soldering tin	ne 5 sec. Max. prefe	ormed
-	ling process is required betwee	en 1 st and 2 nd soldering processes.		
4. Lead-Free Soldering				
For Reflow Solder	0			
1	:150-180°C,120sec.Max.			
	p:Temperature Of Soldering Po	ot Over 230 (),40sec.Max.		
3 · Peak Temperate				
-	ion:2 Times Max.			
5 \ Suggest Solder	Paste Formula 93.3 Sn/3.1 Ag	g/3.1 Bi /0.5 Cu		
For Soldering Iron	(Not Recommended) :			
1 \ Iron Tip Temp:	350°C Max.			
2 Soldering Iron:	30w Max.			
3 Soldering Time	:3 Sec. Max. One Time.			
For Dip Soldering	:			
1 Pre-Heat Temp	:150°C Max. 120 Sec. Max.			
2 • Bath Temp:265	°C Max.			
3 • Dip Time:5 Sec	e. Max.			
5. Drive Method				
Circuit	model A	Circuit model B		
			<u> </u>	
			-	
(A)Recommended	circuit.			
(B)The difference of	of brightness between LED's of	could be found due to the Vf-If characte	ristics of LED.	
	D0 71 02 0005		.	
DRAWING NO. :	DS-71-03-0005	DATE : 2024-1-24	PAGE	12 of 12